

## UNISONIC TECHNOLOGIES CO., LTD

11NM65-U2

**Preliminary** 

**Power MOSFET** 

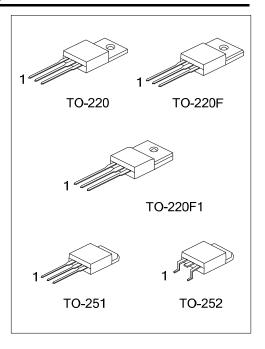
# 11A, 650V N-CHANNEL SUPER-JUNCTION MOSFET

#### ■ DESCRIPTION

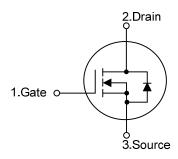
The **UTC 11NM65-U2** is a Super Junction MOSFET Structure and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and a high rugged avalanche characteristics. This power MOSFET is usually used at DC-DC, AC-DC converters for power applications.

#### **■** FEATURES

- \*  $R_{DS(ON)}$  < 0.55 $\Omega$  @  $V_{GS}$ =10V,  $I_{D}$ =5.5A
- \* By using Super Junction Structure
- \* Fast Switching
- \* With 100% Avalanche Tested



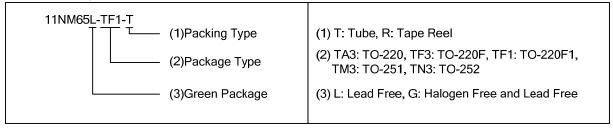
#### ■ SYMBOL



#### ■ ORDERING INFORMATION

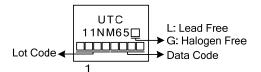
Ordering Number		Dackage	Pin Assignment			Dooking	
Lead Free	Halogen Free	Package	1	2	3	Packing	
11NM65L-TA3-T	11NM65G-TA3-T	TO-220	G	D	S	Tube	
11NM65L-TF3-T	11NM65G-TF3-T	TO-220F	G	D	S	Tube	
11NM65L-TF1-T	11NM65G-TF1-T	TO-220F1	G	D	S	Tube	
11NM65L-TM3-T	11NM65G-TM3-T	TO-251	G	D	S	Tube	
11NM65L-TN3-R	11NM65G-TN3-R	TO-252	G	D	S	Tape Reel	

Note: Pin Assignment: G: Gate D: Drain S: Source



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#### MARKING



#### ■ ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> =25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		$V_{DSS}$	650	V
Gate-Source Voltage		$V_{GSS}$	±30	V
Drain Current	Continuous	I <sub>D</sub>	11	Α
	Pulsed (Note 2)	I <sub>DM</sub>	44	Α
Avalanche Energy	Single Pulsed (Note 3)	E <sub>AS</sub>	358	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	18	V/ns
Power Dissipation	TO-220		156	W
	TO-220F/TO-220F1	$P_{D}$	25	W
	TO-251/TO-252		60	W
Junction Temperature		TJ	+150	°C
Storage Temperature Range		T <sub>STG</sub>	-55 ~ +150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Repetitive Rating : Pulse width limited by maximum junction temperature.
- 3. L=132mH,  $I_{AS}$ =2.33A,  $V_{DD}$ = 50V,  $R_{G}$ =25 $\Omega$ , Starting  $T_{J}$ =25 $^{\circ}$ C
- 4.  $I_{SD} \le 11A$ , di/dt  $\le 200A/\mu s$ ,  $V_{DD} \le BV_{DSS}$ , Starting  $T_J = 25$ °C

#### ■ THERMAL DATA

PARAMETER		SYMBOL	RATING	UNIT	
Junction to Ambient	TO-220/TO-220F TO-220F1	$\theta_{JA}$	62.5	°C/W	
	TO-251/TO-252		110		
Junction to Case	TO-220		0.8	°C/W	
	TO-220F/TO-220F1	$\theta_{JC}$	5.0		
	TO-251/TO-252		2.08		

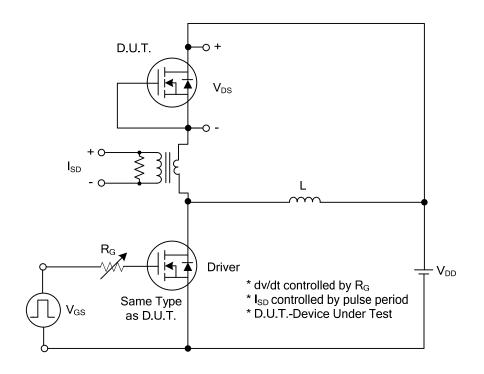
### ■ ELECTRICAL CHARACTERISTICS (T<sub>J</sub>=25°C, unless otherwise specified)

PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage		$BV_{DSS}$	$V_{GS}$ =0V, $I_D$ =250 $\mu$ A	650			V
Drain-Source Leakage Current		I <sub>DSS</sub>	V <sub>DS</sub> =650V, V <sub>GS</sub> =0V			10	μΑ
Gate-Source Leakage Current	Forward		$V_{DS}$ =0V , $V_{GS}$ =30V			100	nA
	Reverse	I <sub>GSS</sub>	$V_{DS}$ =0V , $V_{GS}$ =-30V			-100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage		$V_{GS(TH)}$	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$	2.5		4.5	V
Drain-Source On-State Resistance		R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =5.5A			0.55	Ω
DYNAMIC PARAMETERS	_				ā.		
Input Capacitance	nput Capacitance				610		pF
Output Capacitance		Coss	$V_{GS}$ =0V, $V_{DS}$ =25V, f=1.0MHz		377		pF
Reverse Transfer Capacitance		$C_{RSS}$			27		pF
SWITCHING PARAMETERS	_				ā.		
Total Gate Charge (Note 1)		$Q_G$	V <sub>DS</sub> =50V, V <sub>GS</sub> =10V, I <sub>D</sub> =1.3A ,		40		nC
Gate to Source Charge		$Q_GS$	I <sub>G</sub> =100µA (Note 1, 2)		4.6		nC
Gate to Drain Charge		$Q_GD$	IG-100μΑ (Note 1, 2)		12.8		nC
Turn-ON Delay Time (Note 1)		$t_{D(ON)}$			74		ns
Rise Time		$t_R$	$V_{DD}$ =30V, $V_{GS}$ =10V, $I_{D}$ =0.5A,		94		ns
Turn-OFF Delay Time		$t_{D(OFF)}$	R <sub>G</sub> =25Ω (Note 1, 2)		254		ns
Fall-Time		$t_{F}$			116		ns
SOURCE- DRAIN DIODE RATIN	NGS AND CH	ARACTERIS'	TICS				
Maximum Body-Diode Continuous Current		Is				11	Α
Maximum Body-Diode Pulsed Current		I <sub>SM</sub>				44	Α
Drain-Source Diode Forward Voltage (Note 1)		$V_{\text{SD}}$	I <sub>S</sub> =11A, V <sub>GS</sub> =0V			1.4	V
Body Diode Reverse Recovery Time (Note 1)		t <sub>rr</sub>	I <sub>S</sub> =11A, V <sub>GS</sub> =0V,		358		ns
Body Diode Reverse Recovery Charge		$Q_{rr}$	dI <sub>F</sub> /dt=100A/μs		4.8		μC

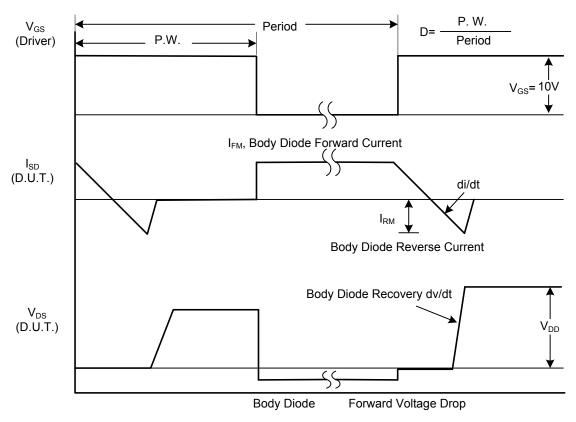
Notes: 1. Pulse Test : Pulse width ≤ 300µs, Duty cycle ≤ 2%.

<sup>2.</sup> Essentially independent of operating temperature.

#### ■ TEST CIRCUITS AND WAVEFORMS

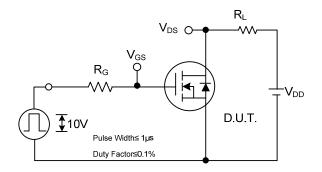


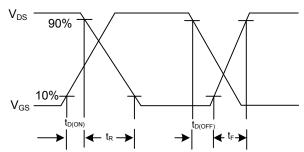
#### Peak Diode Recovery dv/dt Test Circuit



Peak Diode Recovery dv/dt Waveforms

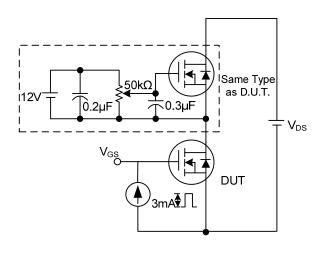
■ TEST CIRCUITS AND WAVEFORMS (Cont.)

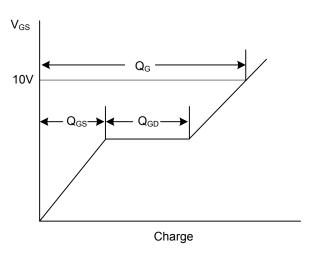




**Switching Test Circuit** 

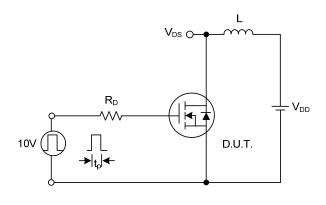
**Switching Waveforms** 

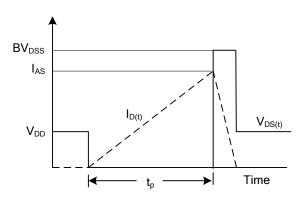




**Gate Charge Test Circuit** 

**Gate Charge Waveform** 





**Unclamped Inductive Switching Test Circuit** 

**Unclamped Inductive Switching Waveforms** 

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